

Cree® Product Change Notification

Customer Name: XXXXXXXXXXXXXXXX	PCN Reference Number: CREE-PCN-1049
Customer Contact: XXXXXXXXXXXXXXXX	Date Issued: XX/XX/20XX
Customer E-Mail:	
Address: Address 1	
Address 2	
City, State Zip	
Country	

Please be advised that Cree has qualified a Major Change to a selection of GaN RF devices and that we will begin shipping the affected product with the change as early as 30 days after the PCN Issue Date.

Please review the additional PCN information below.

Affected Product

Table 1 provides a list of products affected by this Major change:

Table 1 Affected Products List

Cree Part Number	Cree Part Number	Cree Part Number	Cree Part Number
CGH21120F	CGHV31500F	CGHV59350F	CMPA2560025F
CGH25120F	CGHV35150F	CGHV96050F1	CMPA5259025F
CGHV141K0F	CGHV35150P	CGHV96050F2	CMPA5259050F
CGHV14250F	CGHV35400F	CGHV96100F2	CMPA5585025F
CGHV14500F	CGHV37400F	CGHV96130F	CMPA5585030F
CGHV14800F	CGHV50200F	CMPA0060002F	CMPA601C025F
CG2H40120F	CG2H40025P	CMPA0060025F	CMPA801B025F
CG2H40010P			

Description of the Change

In March of 2018, Cree announced the acquisition of Infineon’s RF Power business. This acquisition included manufacturing facilities. The main facility is in Morgan Hill (MGH), California which includes packaging and test operations for LDMOS and GaN-on-SiC RF components.

Cree intends to begin the use of Morgan Hill as an alternate manufacturing site for our RF components. Cree’s Research Triangle Park (RTP) manufacturing site will also continue packaging and test operations.

The appearance of the devices manufactured in Morgan Hill will look different, only in the lid marking and lot number format.



Fabrication of the semiconductor die will not change. GaN-on-SiC die will continue to be fabricated on the Cree campus in North Carolina. The affected RF components are listed in table 1.

The following parameters will see no change:

1. Product's Bill of Materials
2. DC and RF parameters
3. Data sheet specifications
4. Certificates of Compliance

Labels from the Cree Morgan Hill factory are slightly different than Cree RTP labels. Below are examples of Shipping Container Label (Figure 1) and the individual tray or reel label (Figure 2).

Shipping Container Label (Figure 1)

(1T) is the Master Ship Lot (MSL). This lot number is for the shipment. A shipment can contain many sub-lots (Figure 2) for product inside the container.

The MSL format is MSLnnnnnnYY

nnnnnn is the sequential number

YY is Year, last 2 digits

(1P) is the Product Part Number

(9D) is the Date Code YYMM

(Q) is the Quantity of parts inside the container.

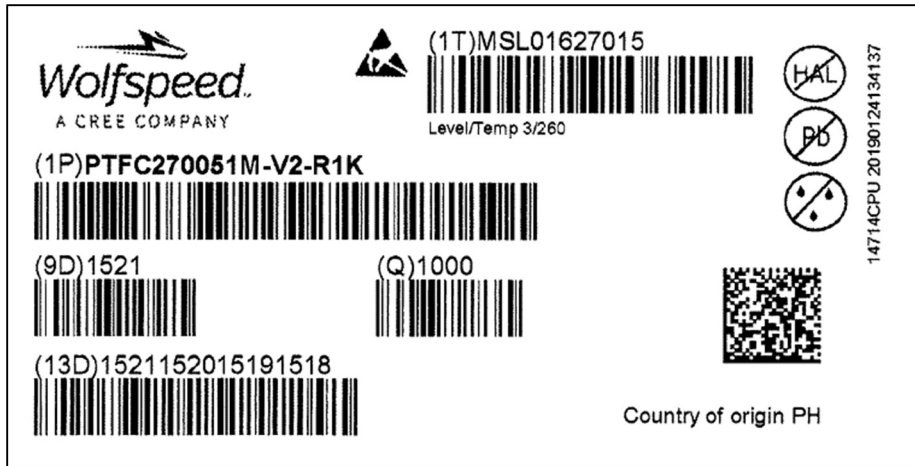


Figure 1 – Label on the exterior of the shipping container

Individual Tray or Reel Label (Figure 2)

Tray and Reel labels (Figure 2) include a bar code. The bar code is in the format : %\$<part>\$<lot>\$Q<qty>\$%. For the example label below, the read-out is %\$CGH40025F\$M1923499\$Q34\$%



Figure 2 – Label on the individually bagged trays or reels.

Reason for the Change

This letter is to inform you that Cree will establish an alternate assembly and test facility for its RF components.

Change Impact on Form, Fit, Function, or Reliability

The device markings, shipping containers and shipping labels will change as indicated above.

Key Dates

Table 2 provides estimated dates for Key PCN Milestones based on information available at the date the PCN was issued. Any updates to these dates can be provided by the Cree contact listed in Table 3.

Table 2 Key PCN Estimated Dates

Qualification Report Availability	2020
Sample Availability	Beginning 4/1/2020
Proposed First Ship Date	Beginning 4/1/2020
Last Date of Unchanged Product	N/A since this is an alternate site

Cree Contact Information

If you have any questions regarding this Major PCN please contact:

Table 3 PCN Contact

Cree Contact:	Ryan Baker
Cree Contact E-Mail:	Ryan_Baker@cree.com
Cree Contact Phone:	919.407.7816
Cree Contact Fax Number:	N/A
Address:	4600 Silicon Drive Durham NC, 27703 USA